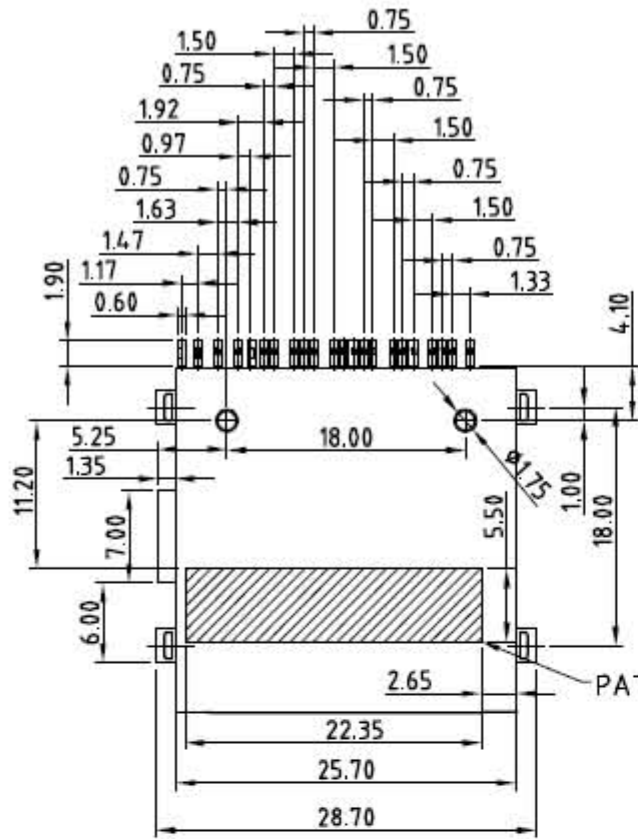
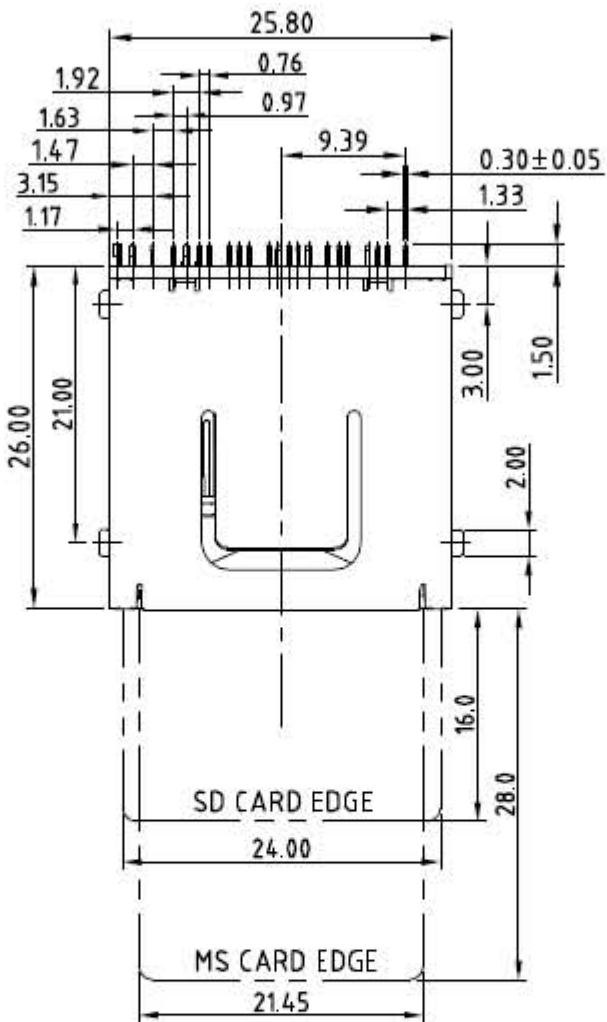
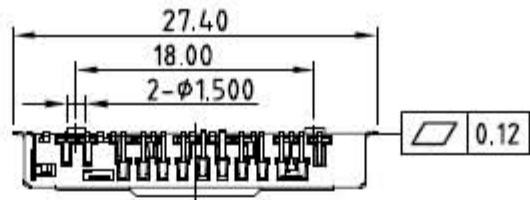
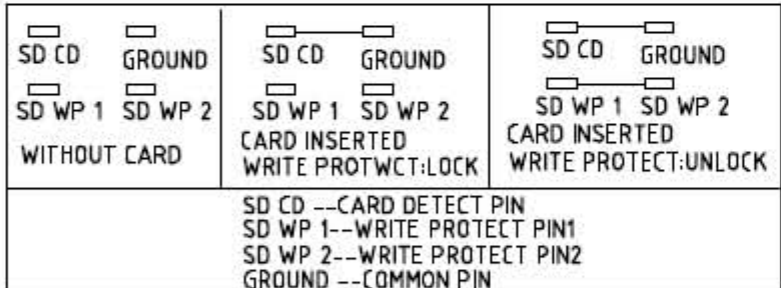


TIME:SD+MS



P.C.B Layout

SD CARD CIRCUIT



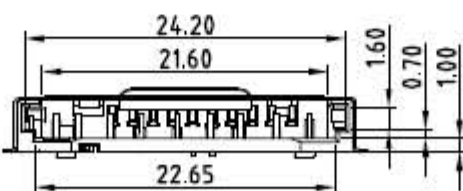
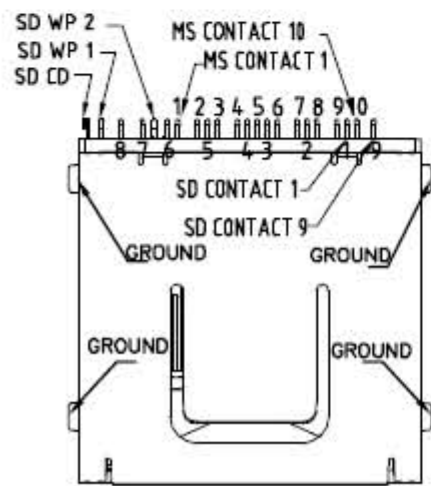
MS PIN DESIGN

| Pin No. | MS CARD Name | MS PRO Name |
|---------|--------------|-------------|
| 1#      | VSS          | VSS         |
| 2#      | BS           | BS          |
| 3#      | VCC          | DATE1       |
| 4#      | DIO          | DATE0       |
| 5#      | RESERVE      | DATE2       |
| 6#      | INS          | INS         |
| 7#      | RESERVE      | DATE3       |
| 8#      | SCLK         | SCLK        |
| 9#      | VCC          | VCC         |
| 10#     | VSS          | VSS         |

SD CARD PIN DESIGN

| Pin No. | Name    | Description          |
|---------|---------|----------------------|
| 1#      | CD/DAT3 | Card detect/Data I/O |
| 2#      | CMD     | Command              |
| 3#      | VSS1    | Ground               |
| 4#      | VDD     | Power                |
| 5#      | CLK     | Clock                |
| 6#      | VSS2    | Ground               |
| 7#      | DAT0    | Data I/O             |
| 8#      | DAT1    | Data I/O             |
| 9#      | DAT2    | Data I/O             |

- ANOTES:
- 1.MATERIAL  
HOUSING: HIGH TEMPERATURE THERMOPLASTIC.  
CONTACT: COPPER ALLOY.  
SHELL: COPPER ALLOY.
  - 2.PLATING  
CONTACT AREA: GOLD PLATED OVER Ni.  
SOLDER TAIL: 100 u" MIN Sn PLATED OVER Ni.  
SPEC SEE ORDERING INFORMATION.
  - 3.RATING  
CURRENT RATING: 0.5A  
VOLTAGE RATING: 250VRM  
OPERATING TEMPERATURE:-25°C~90°C
  - 4.SPECIFICATION  
CONTACT RESISTANCE: 100mΩ Max  
DIELECTRIC WITHSTANDING VOLTAGE: 500VAC  
INSULATION RESISTANCE: 100MΩ Min  
INSERTION FORCE: 40N MAX.  
SEPARATION FORCE: 0.98N MIN.



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